



Material Content Data Sheet



Sales Product Name				IAUC120N04S6N009		Issued		14. September 2018	
MA#				MA003530726					
Package				PG-TDSON-8-43		Weight*		117.58 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.155	1.83	1.83	18325	18325	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127		
	non noble metal	iron	7439-89-6	0.050	0.04		424		
	non noble metal	copper	7440-50-8	49.837	42.41	42.46	423843	424394	
	noble metal	gold	7440-57-5	0.027	0.02	0.02	226	226	
wire	organic material	carbon black	1333-86-4	0.065	0.05		549		
encapsulation	plastics	epoxy resin	-	5.097	4.33		43345		
	inorganic material	silicondioxide	60676-86-0	27.096	23.04	27.42	230441	274335	
leadfinish	non noble metal	tin	7440-31-5	1.283	1.09	1.09	10909	10909	
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1779	1779	
solder	non noble metal	tin	7440-31-5	0.065	0.05		549		
	noble metal	silver	7440-22-4	0.067	0.06		571		
heat sink CLIP	non noble metal	lead	7439-92-1	2.555	2.17	2.28	21733	22853	
	inorganic material	phosphorus	7723-14-0	0.009	0.01		74		
	non noble metal	iron	7439-89-6	0.029	0.02		247		
	non noble metal	copper	7440-50-8	29.026	24.69	24.72	246858	247179	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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